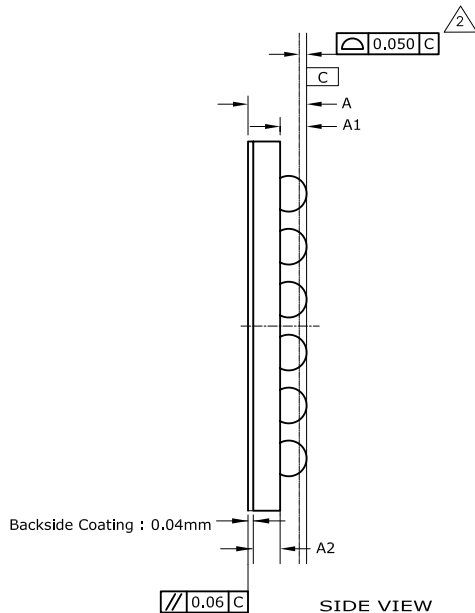
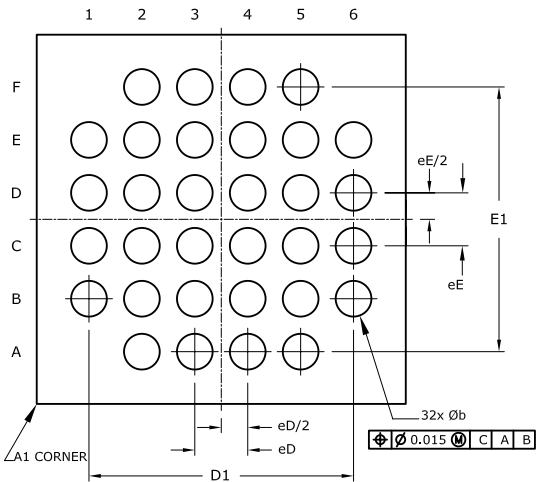


TOP VIEW



SIDE VIEW



BOTTOM VIEW

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Bump Pitch	eD	0.40 BSC		
Bump Pitch	eE	0.40 BSC		
Length	D	2.79 BSC		
Width	E	2.79 BSC		
Overall Height	A	0.404	0.443	0.482
Bump Height	A1	0.17	----	0.23
Die Thickness	A2	0.178	0.203	0.228
Bump Diameter	b	0.24	0.27	0.30
Edge Ball Center to Center	D1	2.00 BSC		
	E1	2.00 BSC		

- Notes : 1. Dimension "b" is measured at the maximum ball diameter in a plane to the seating plane.  
 2. Applied to whole wafer.

01/15/2018



Package Drawing Contact:  
 packagedrawings@atmel.com

TITLE

VT, 32 ball (6x6 Array, minus 4 balls), 0.4mm pitch  
 2.79 x 2.79 x 0.482mm, WLCPSP

GPC

DRAWING NO.

REV.

GWB

VT

A